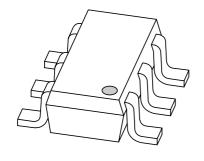
DISCRETE SEMICONDUCTORS

DATA SHEET



PMEG6010AEDLow V_F (MEGA) Schottky barrier diode

Product data sheet 2003 Jun 27



Low V_F (MEGA) Schottky barrier diode

PMEG6010AED

FEATURES

- · Low switching losses
- · Very high surge current absorption capability
- · Fast recovery time
- · Guard ring protected
- Plastic SMD package.

APPLICATIONS

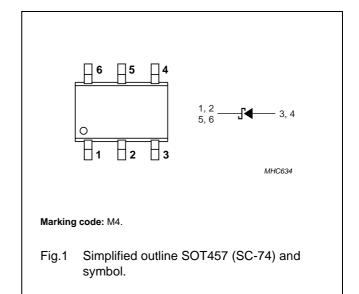
- Low power switched-mode power supplies
- Rectification
- · Polarity protection.

GENERAL DESCRIPTION

Planar Schottky barrier diode encapsulated in a SOT457 (SC-74) small plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	cathode
3	anode
4	anode
5	cathode
6	cathode



LIMITING VALUES

In accordance with Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	60	V
I _F	continuous forward current	T _{amb} ≤ 25 °C; note 1	_	1	Α
I _{FSM}	non-repetitive peak forward current	t = 8 ms; square wave	_	17.5	Α
I _{RSM}	non-repetitive peak reverse current	t _p = 100 μs	_	0.5	Α
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	+150	°C

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for cathode 6 cm².

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ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V _F	continuous forward voltage	I _F = 0.1 A	400	mV
		I _F = 1 A	650	mV
I _R	continuous reverse current	V _R = 60 V; see Fig.3	350	μΑ
		V _R = 60 V; T _j = 100 °C; notes 1 and 2	8	mA
C _d	diode capacitance	$V_R = 4 \text{ V}$; f = 1 MHz; see Fig.4	60	pF

Notes

- 1. Pulse test: t_p = 300 μ s; δ = 0.02.
- 2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications, the reverse power losses P_R are a significant part of the total power losses.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air; note 1	230	K/W
		in free air; note 2	180	K/W

Notes

- 1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for cathode 1 cm².
- 2. Device mounted on a printed-circuit board, single-sided copper; tinplated, mounting pad for cathode 6 cm².

Low V_F (MEGA) Schottky barrier diode

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GRAPHICAL DATA

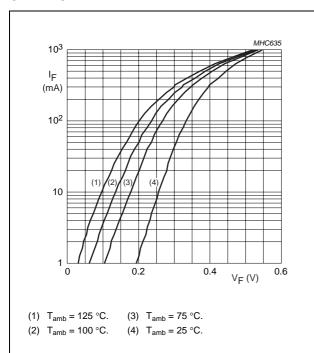
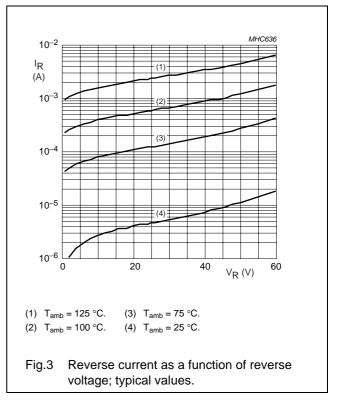
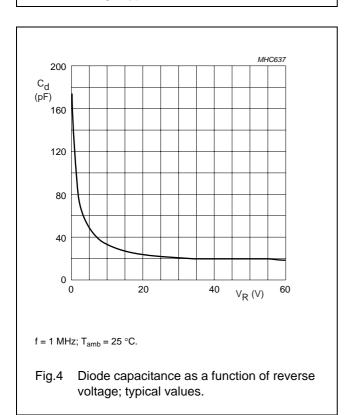


Fig.2 Forward current as a function of forward voltage; typical values.





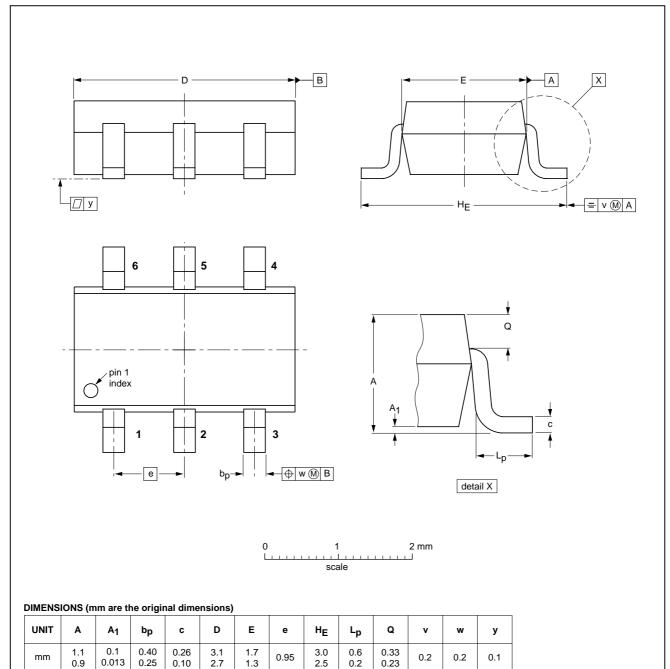
Low V_F (MEGA) Schottky barrier diode

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PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT457



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT457			SC-74			97-02-28 01-05-04

Low V_F (MEGA) Schottky barrier diode

PMEG6010AED

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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